DB3X407K

Silicon epitaxial planar type

For high frequency rectification

■ Features

- Short reverse recovery time t_{rr}
- Low forward voltage V_F
- Halogen-free / RoHS compliant (EU RoHS / UL-94 V-0 / MSL: Level 1 compliant)

■ Marking Symbol: 3J

■ Packaging

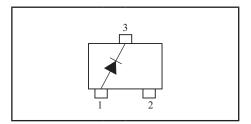
DB3X407K0L Embossed type (Thermo-compression sealing): 3 000 pcs / reel (standard)

■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit	
Reverse voltage	V _R	40	V	
Maximum peak reverse voltage	V _{RM}	40	V	
Forward current (Average)	I _{F(AV)}	500	mA	
Non-repetitive peak forward surge current *1	I_{FSM}	2	A	
Junction temperature	T_j	125	°C	
Operating ambient temperature	T _{opr}	-40 to +85	°C	
Storage temperature	T _{stg}	-55 to +125	°C	

Note) *1: 50 Hz sine wave 1 cycle (Non-repetitive peak current)

Unit: mm 2. 9 0. 4 0. 16 (0. 95) (0. 95) 1. 9 1: Anode 2: N.C. 3: Cathode Panasonic Mini3-G3-B JEITA SC-59A Code TO-236AA/SOT-23

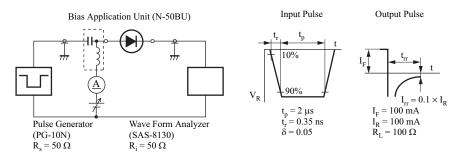


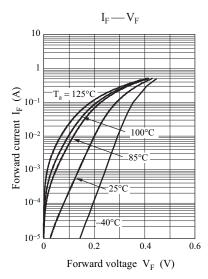
■ Electrical Characteristics $T_a = 25$ °C±3°C

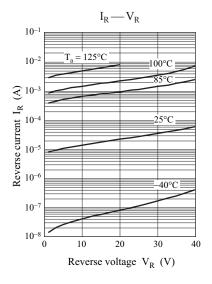
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	$V_{\rm F}$	$I_F = 500 \text{ mA}$			0.55	V
Reverse current	I_R	$V_R = 35 V$			100	μΑ
Terminal capacitance	C _t	$V_R = 10 \text{ V}, f = 1 \text{ MHz}$		10.5		pF
Reverse recovery time *1	t _{rr}	$\begin{aligned} I_F &= I_R = 100 \text{ mA}, I_{rr} = 0.1 \times I_R, \\ R_L &= 100 \Omega \end{aligned}$		3.6		ns

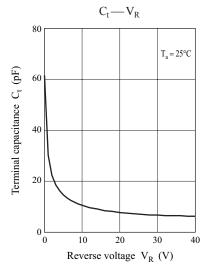
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

- 2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.
- 3. Absolute frequency of input and output is 400 MHz
 - *1: t_{rr} measurement circuit



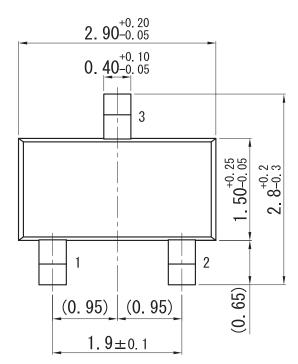


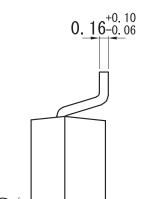


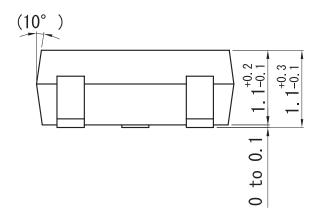


Unit: mm

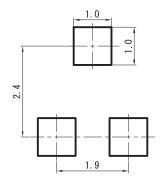
Mini3-G3-B







■ Land Pattern (Reference) (Unit: mm)



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